

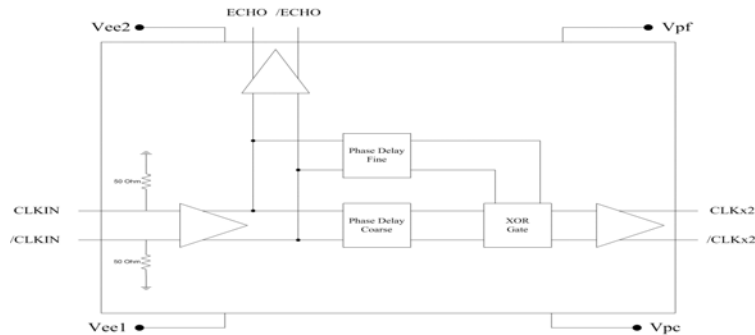
### Description

The iT4134D is a high-speed X2 clock multiplier fabricated using 1- $\mu\text{m}$  HBT GaAs technology and employs an ECL topology to guarantee high-speed operation. It is an excellent choice for digital clock multiplication, instrumentation, and edge detection. Digital clock multiplication is implemented via XOR operation between the input clock and an internal delayed replica. Several embedded electrically-controlled phase delays are also employed. Suitable regulation of the phase delay voltage controls allows duty cycle control on the clock outputs. Suitable power supply internal distribution provides the ability to disable the echo input which reduces power consumption. The iT4134D can also be stimulated via NRZ data to perform edge detection. A dedicated temperature monitoring pin is also provided.

### Features

- ❖ Clock input range: 4 to 7 GHz
- ❖ 900 mVpp typical single-ended output
- ❖ Input sensitivity: Single-ended input >200 mV
- ❖ Jitter RMS <1 ps
- ❖ 50-ohm matched inputs and outputs (DC)
- ❖ Compatible SCFL I/O levels
- ❖ Differential or single-ended I/O
- ❖ Duty cycle control
- ❖ Echo inputs available
- ❖ Power consumption: 1.25 W

### Device Diagram



### Absolute Maximum Ratings

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this document is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Symbol	Parameters/conditions	Min.	Max.	Units
$V_{EE}$	Power supply voltage	-5.5	0	V
$V_{PC}$	Phase delay voltage control (coarse duty cycle adjustment)	-3.5	0	V
$V_{PF}$	Phase delay voltage control (fine duty cycle adjustment)	-3.5	0	V
$V_{IH}$	Data/clock input voltage level, high level	-1.2	1.2	V
$V_{IL}$	Data/clock input voltage level, low level	-1.2	1.2	V
$T_A$	Operating temperature range	-15	125	$^{\circ}\text{C}$
$T_{STG}$	Storage temperature	-65	150	$^{\circ}\text{C}$



# iT4134D

## X2, 4-to-7 GHz Clock Multiplier

(Advanced Information)

### Recommended Operating Conditions

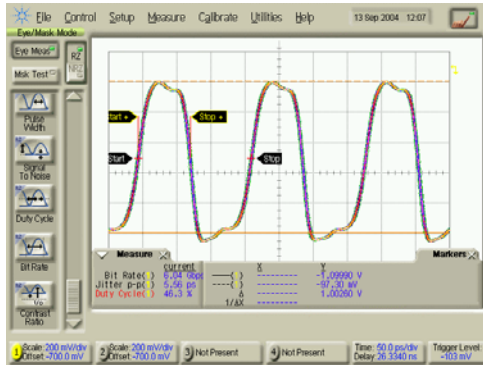
Symbol	Parameters/Conditions	Min.	Typ.	Max	Units
Ta	Operating temperature range	0		85	°C
Vee	Power supply voltage		-5		V
Vih	Data/clock input voltage level, high level (single ended)		0.25		V
Vil	Data/clock input voltage level, low level (single ended)		-0.25		V
Vindc	DC input voltage (with DC-coupled input)		0		V

### Electrical Characteristics

1. Electrical characteristics at ambient temperature.
2. In case of single-ended inputs the unused pin has to be tied to VINDC. In case of single-ended output the unused one has to be terminated via 50 ohms to ground.
3. The pin VPmon can be left open or sensed with high-impedance load for temperature monitoring.
4. In case of echo inputs, an extra 65-mA (325-mW) at -5 V must be taken into account

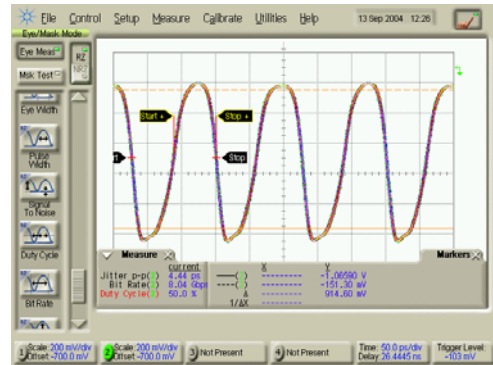
Symbol	Parameters	Min	Typ	Max	Units
Vee	Power supply voltage	-5.25	-5.0	-4.75	V
Vih	Data/clock input voltage level, high level (single ended)	-0.5	0.25	0.5	V
Vil	Data/clock input voltage level, low level (single ended)	-1	-0.25	0	V
Vindc	DC input voltage (with DC-coupled input) <sup>(2)</sup>	-0.75	0	0.25	V
VPmon	Internally generated reference voltage for 0 ps delay offset of the embedded phase delays (coarse and fine). <sup>(3)</sup>	-2.8	-2.6	-2.4	V
VPc	Phase delay voltage control (coarse duty cycle adjustment)	VPmon-0.4		VPmon+0.4	V
VPf	Phase delay voltage control (fine duty cycle adjustment)	VPmon-0.4		VPmon+0.4	V
Voh	Data/clock output voltage level, high level (single ended)	-0.1	0	0	V
Vol	Data/clock output voltage level, low level (single ended)	-1.0	-0.9	0.8	V
Tdc	Duty cycle control	40	50	60	%
RLin	Input return loss (up to 25 GHz)		15		dB
RLout	Output return loss (up to 25 GHz)		6		dB
Fclk	Input clock frequency	3.0		7.0	GHz
Jpp	Peak to peak jitter	4	5	6	ps
Jrms	RMS jitter	0.7	0.9	1	ps
SHS	Sub-harmonic suppression	15	20	25	mA
Ic	Power supply current <sup>(4)</sup>	235	250	280	mA
Pd	Power dissipation <sup>(4)</sup>	1.1	1.25	1.5	W

### Eye Diagram Performance



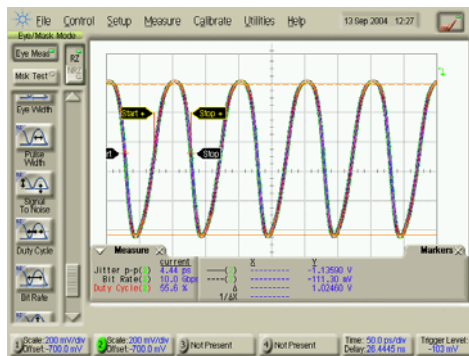
Die measurement  
Vee: -5.0 V

Clock input frequency: 3.0 GHz  
Single-ended clock input: +/-250 mVpp



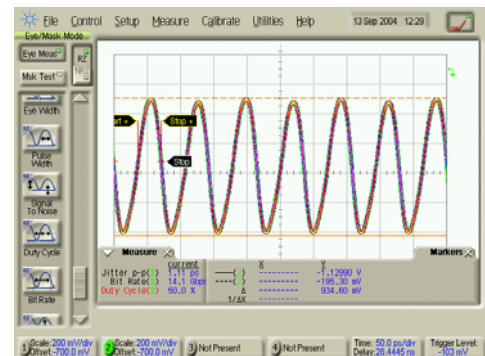
Die measurement  
Vee: -5.0 V

Clock input frequency: 4.0 GHz  
Single-ended clock input: +/-250 mVpp



Die measurement  
Vee: -5.0 V

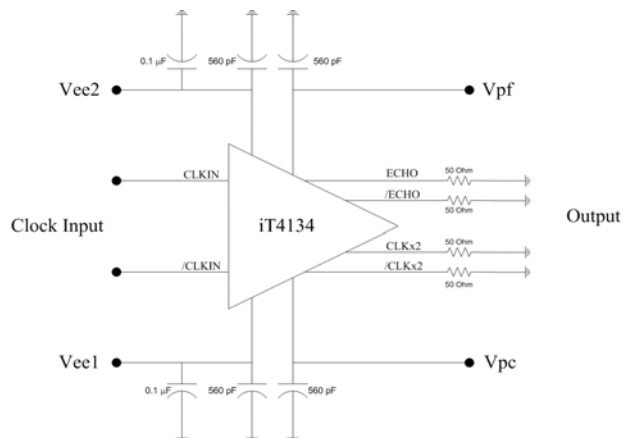
Clock input frequency: 5.0 GHz  
Single-ended clock input: +/-250 mVpp



Die measurement  
Vee: -5.0 V

Clock input frequency: 7.0 GHz  
Single-ended clock input: +/-250 mVpp

### Recommended Operational Setup



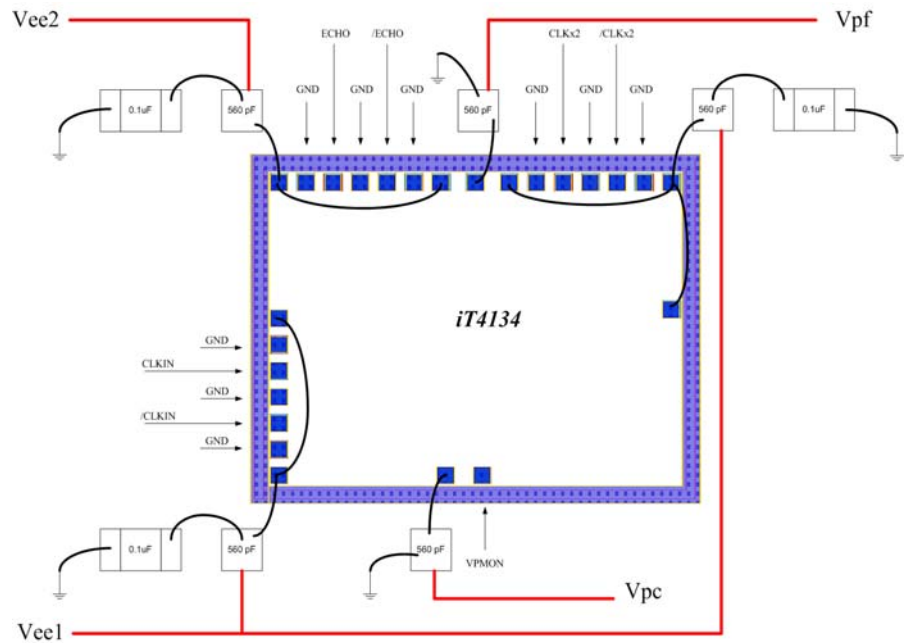
### Recommended Mounting Assembly

Chip size  
1900  $\mu\text{m} \pm 10 \mu\text{m}$   
 $\times$  2400  $\mu\text{m} \pm 10 \mu\text{m}$   
edge to edge

Chip thickness:  
104  $\mu\text{m} \pm 3 \mu\text{m}$

Pad size:  
100  $\mu\text{m} \times 100 \mu\text{m}$

RF pad pitch:  
150  $\mu\text{m}$



### Pad Position and Chip Dimensions

Chip size  
1900  $\mu\text{m} \pm 10 \mu\text{m}$   
 $\times$  2400  $\mu\text{m} \pm 10 \mu\text{m}$   
edge to edge

Chip thickness:  
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